

TIDA-01596 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
PCB1	1		TIDA-01596	Any	Printed Circuit Board	
C1	1	330uF	T495C337K004ATE700	Kemet	CAP, TA, 330 µF, 4 V, +/- 10%, 0.7 ohm, SMD	6032-28
C2, C7	2	0.1uF	C0603X5R0J104K030BC	TDK	CAP, CERM, 0.1 uF, 6.3 V, +/- 10%, X5R, 0201	0201
C3	1	0.47uF	CL03A474KQ3NNNC	Samsung Electro-Mechanics	CAP, CERM, 0.47 uF, 6.3 V, +/- 10%, X5R, 0201	0201
C4, C8	2	0.1uF	CL03A104KP3NNNC	Samsung Electro-Mechanics	CAP, CERM, 0.1 uF, 10 V, +/- 10%, X5R, 0201	0201
C5, C9	2	1500pF	GRM033R61A152KA01D	MuRata	CAP, CERM, 1500 pF, 10 V, +/- 10%, X5R, 0201	0201
C6	1	0.22uF	GRM155R60J224KE01D	MuRata	CAP, CERM, 0.22 uF, 6.3 V, +/- 10%, X5R, 0402	0402
C12, C13, C14, C15, C16	5	0.01uF	GRM033R60J103KA01D	MuRata	CAP, CERM, 0.01 uF, 6.3 V, +/- 10%, X5R, 0201	0201
H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
J1, J2, J3, J4, J6	5		61300211121	Würth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650 x 0.200 inch
LEFT1, RIGHT1	2		SSQ-110-03-T-D	Samtec	Receptacle, 2.54mm, 10x2, Tin, TH	10x2 Receptacle
R1	1	56.0k	CRCW020156K0FKED	Vishay-Dale	RES, 56.0 k, 1%, 0.05 W, 0201	0201
R2, R4	2	1.1	RC0201JR-071R1L	Yageo America	RES, 1.1, 5%, 0.05 W, 0201	0201
R3	1	0.05	LVK24R050DER	Ohmite	RES, 0.05, 0.5%, 1 W, 2412	2412
R5, R6	2	24.9	RC0201FR-0724R9L	Yageo America	RES, 24.9, 1%, 0.05 W, 0201	0201
R7	1	20	AC07000002009JAC00	Vishay-Dale	RES, 20, 5%, 7 W, Axial resistor	Axial resistor
SH-J1, SH-J2, SH-J3, SH-J4	4		60900213521	Würth Elektronik	Shunt, 2.54mm, Gold, Red	Shunt, 2.54mm, Red
TP1, TP2, TP3, TP4, TP5, TP6, TP7	7		S1751-46	Harwin	Test Lead clips and hooks, SMT	Test Point, Body 3.25x1.65mm
U1	1		INA230AIRGTR	Texas Instruments	28-V, Bi-Directional, Zero-Drift, Low-/High-Side, I2C Out Current/Power Monitor w/ Alert, RGT0016C (VQFN-16)	RGT0016C
U2, U4	2		TMP235DCK	Texas Instruments	TMP235DCK, DCK0005A (SOT-5)	DCK0005A
U3	1		ADS7142IRUGR	Texas Instruments	Nanopower, Ultra-Small Size, Sensor Monitor with I2C Interface and Alert Output, RUG0010A (X2QFN-10)	RUG0010A
U6, U7, U8, U9, U10	5		LMT84LPGM	Texas Instruments	Analog Temperature Sensor with Class-AB Output, LPG0003A (TO-92-3)	LPG0003A
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A
R8, R9	0	0	ERJ-1GE0R00C	Panasonic	RES, 0, 5%, 0.05 W, 0201	0201

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